

Method for bonding and debonding of substrates

Abstract

The invention relates to a method for bonding a product substrate (2) to a carrier substrate (5) via a connection layer (4), wherein a soluble layer (3) is applied between the connection layer (4) and the product substrate (2), and wherein

- a) the soluble layer (3) is soluble due to an interaction with an electromagnetic radiation of a radiation source and
- b) the connection layer (4) and the carrier substrate (5) are at least predominantly transparent to the electromagnetic radiation.

Furthermore the invention relates to a method for debonding a product substrate (2) from a carrier substrate (5) bonded to the product substrate (2) via a connection layer (4) wherein a soluble layer (3) is applied between the connection layer (4) and the product substrate (2), and wherein

- a) the soluble layer (3) is dissolved through an interaction with an electromagnetic radiation of a radiation source, and
- b) the connection layer (4) and the carrier substrate (5) are at least predominantly transparent to the electromagnetic radiation.

Furthermore the present invention relates to a corresponding product-substrate-to-carrier-substrate bond.

Figure 1b.